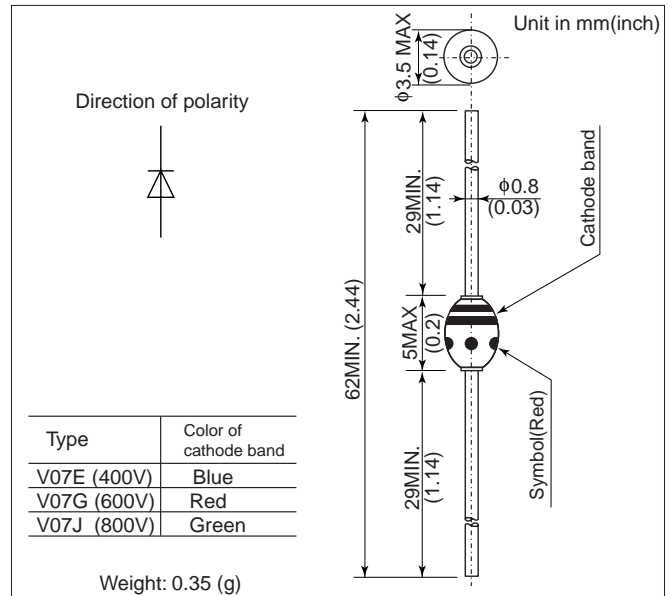


V07

FEATURES

- Transient surge voltage protection.
- Diffused-junction. Glass passivated and encapsulated.

OUTLINE DRAWING



ABSOLUTE MAXIMUM RATINGS

| Items | Type | V07E | V07G | V07J |
|---------------------------------------|-------------|----------------------|---|------|
| Repetitive Peak Reverse Voltage | V_{RRM} | V | 400 | 600 |
| Peak Reverse Power | P_{RM} | W | 40($T_j = 165^\circ\text{C}$, Pulse duration 1ms Non-repetitive) | |
| Average Forward Current | $I_{F(AV)}$ | A | 1.3 (Single-phase half sine wave 180° conduction $T_L=90^\circ\text{C}$, Lead length = 10mm) | |
| Surge(Non-Repetitive) Forward Current | I_{FSM} | A | 40(Without PIV, 10ms conduction, $T_j = 175^\circ\text{C}$ start) | |
| I^2t Limit Value | I^2t | A^2s | 6.4(Time = 2 ~ 10ms, I = RMS value) | |
| Operating Junction Temperature | T_j | $^\circ\text{C}$ | -65 ~ +175 | |
| Storage Temperature | T_{stg} | $^\circ\text{C}$ | -65 ~ +200 | |

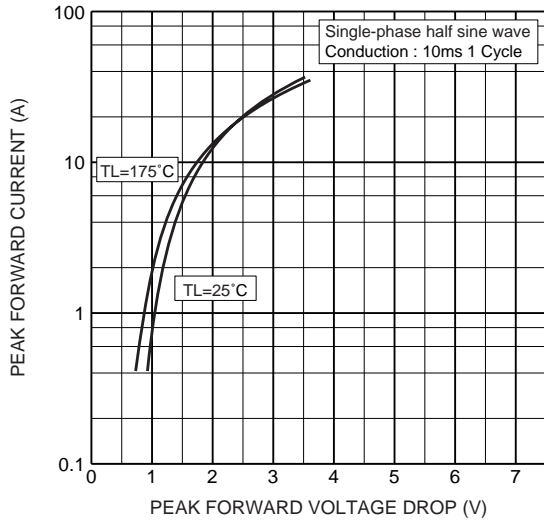
Notes (1) Lead mounting : Lead temperature 300°C max. to 3.2mm from body for 5sec. max..

(2) Mechanical strength : Bending $90^\circ \times 2$ cycles or $180^\circ \times 1$ cycle, Tensile 2kg, Twist $90^\circ \times 1$ cycle.

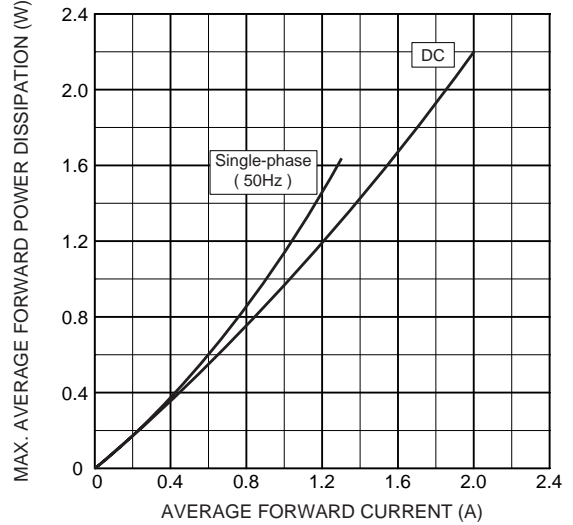
CHARACTERISTICS($T_L=25^\circ\text{C}$)

| Items | Symbols | Units | Min. | Typ. | Max. | Test Conditions |
|--------------------------------|---------------|--------------------|-----------|------|------|--|
| Peak Reverse Current | I_{RRM} | μA | — | 0.6 | 10 | All class, Rated V_{RRM} |
| Peak Forward Voltage | V_{FM} | V | — | — | 1.1 | $I_{FM}=1.3A_p$, Single-phase half sine wave 1 cycle |
| Reverse Recovery Time | t_{rr} | μs | — | 3.0 | — | $I_F=2\text{mA}$, $V_R=-15\text{V}$ |
| Avalanche Voltage | V_{AVL} | V | V_{RRM} | — | 1600 | $I_{RM}=1.0\text{mA}$, Single-phase half sine wave 1 pps, Time $\leq 5\text{s}$ |
| Steady State Thermal Impedance | $R_{th(j-a)}$ | $^\circ\text{C/W}$ | — | — | 80 | Lead length = 10 mm |
| | $R_{th(j-l)}$ | | | | 50 | |

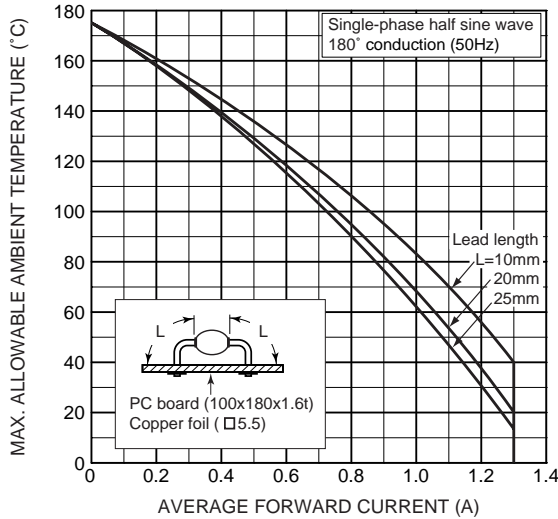
Forward characteristics



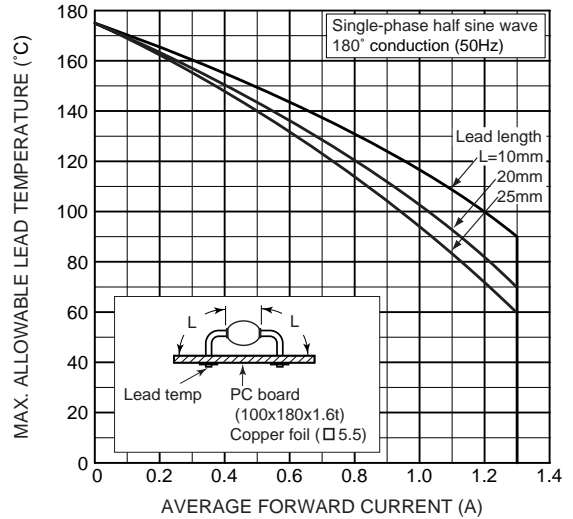
Max. average forward power dissipation (Resistive or inductive load)



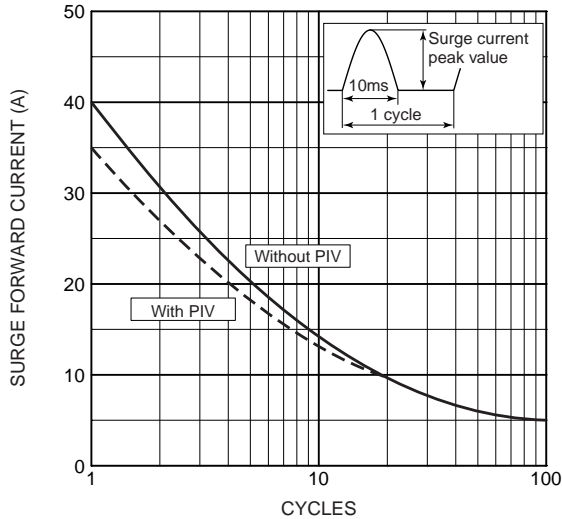
Max. allowable ambient temperature (Resistive or inductive load)



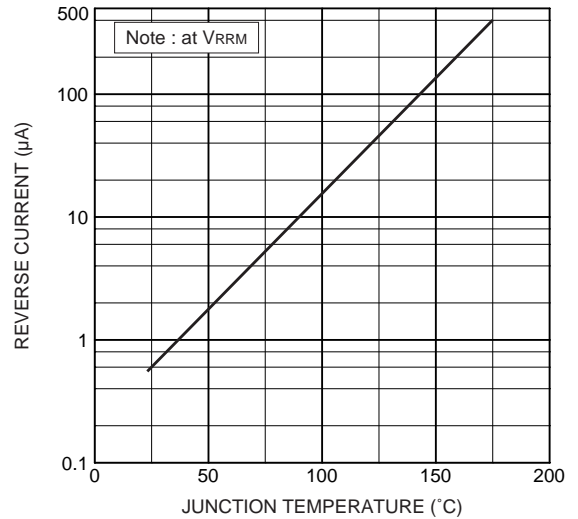
Max. allowable lead temperature (Resistive or inductive load)



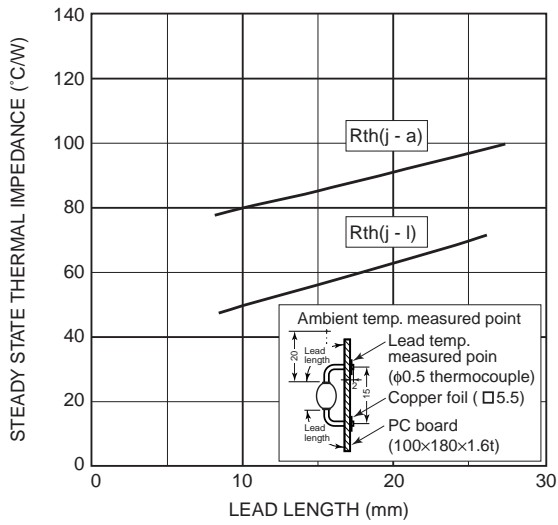
Surge forward current characteristic (Non-repetitive)



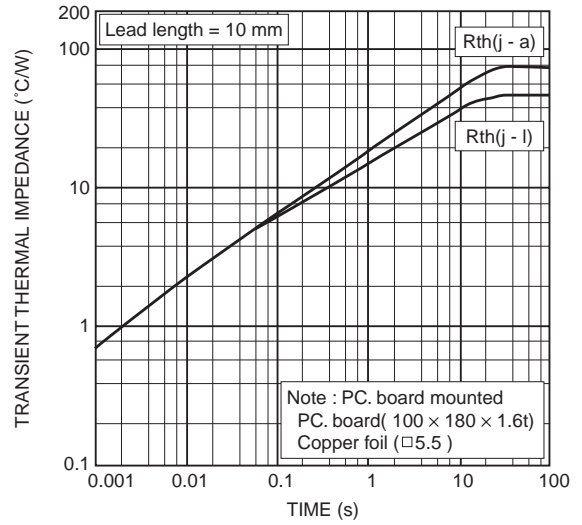
Typ. Reverse current vs. junction temperature



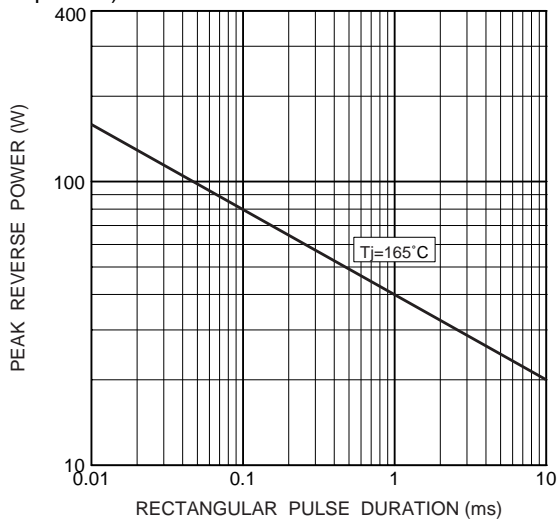
Steady-state thermal impedance



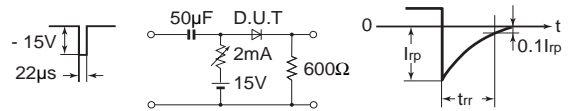
Transient thermal impedance



Typical reverse power characteristic (Non-repetitive)



Reverse recovery time (t_{rr}) test circuit



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